

## Index

- absorption, 69
- active tuning, 234
- alignment, 394–396
- apodization, 164
- applications, 7
- automated optical probe station, 389–397
- avalanche detector, 268
- back reflection, 164
- band structures, 30
- bandwidth
  - detector, 260
- beam propagation method, 37
- bent waveguides, 69–75
  - field profile, 74
  - mode profile, 74
  - propagation loss, 73
  - rib, 72
  - rib waveguides, 76
  - strip, 71
  - strip waveguides, 76
- bond pads, 386
- bonding, 12
- Bragg gratings, 117–143
- buried oxide, 178
- channel waveguide, *see* strip waveguide
- checklist, 402
- circuit export, 355
- circuit modelling, 313, 317, 330, 333
- cladding, 179
- CMC Microsystems, 22
- combiner, 110
- common-bus WDM, 408
- compact models, 314, 316
- computation lithography models, 134
- contacts, 273
- corner analysis, 370
- coupled mode theory, 38, 92
- coupling coefficient, 92
- cross-over length, 93
- cross-talk, 106–110
- dark current, 262
- data communication, 8, 406
- delta beta coupling, 108, 109
- design for manufacturability, 20
- design for test, 362, 398
- design methodology, 28, 168
- design review, 402
- design rule checking, 350, 360
- design rules, 352
- detector, 13, 259–282
  - avalanche, 268
  - band diagram, 267
  - bandwidth, 260, 273
  - contacts, 273
  - cross-section, 266
  - dark current, 262, 263, 280, 281
  - fabrication, 264
  - FDTD, 275
  - opto-electronic model, 279
  - photoconductive, 266
  - pin, 267
  - responsivity, 259, 266, 267, 273, 281
  - SEM, 265
  - transient, 282
  - transit time, 260
- detectors, 397
- detuned grating, 165
- device design, 17
- directional couplers, 92–110, 318–329
- directionality, 164
- dispersion
  - group velocity dispersion, 66
  - material, 66
  - waveguide, 66
- edge couplers, 182–190, 382
- effective index, 30, 53, 57–59, 61, 66, 68
- effective index method, 30, 57–60
- eigenmode expansion method, 37, 92
- eigenmode solver, 28
- electrical interfaces, 386–389
- electronic design automation, 41
  - mask layout, 42
- electronic simulations, 41

- electronic–photonic co-design, 351
- electronic–photonic integration, 43
- electrons, 9
- ePIXfab, 21
- experimental
  - bends, 70–72
  - Bragg gratings, 126–143, 369
  - detector, 263, 266, 267, 273
  - directional coupler, 99–101
  - eye diagrams, 409, 412
  - fabrication non-uniformity, 372–378
  - free spectral range, 116, 117
  - grating coupler, 181, 373
  - group index, 67, 374
  - ring resonator, 116, 117, 373
- eye diagrams, 409, 412
- fabrication
  - detector, 264
  - fabless, 5, 20
  - non-uniformity, 136, 368–378
  - process contours, 369
  - process parameters, 352
  - sensitivity, 103
- fan-in assembly, 384
- FDTD
  - 2.5D, 36–37
  - 2D, 35
  - 3D, 31–35
  - bends, 70–73
  - description, 31
  - directional couplers, 102–103
  - E-field intensity, 73
  - edge coupler, 187
  - effective index method, 36
  - grating coupler, 171
- fibre array, 384, 385
- fibre grating coupler, *see also* grating coupler, 163–182
- fibre packaging, 382
- fibre taper coupling, 386
- finite difference modelling, 28
- finite different time domain, *see* FDTD
- finite element modelling, 28
- flip-chip bonding, 16, 388
- foundry
  - CEA-Leti, 21
  - electron-beam lithography, 127, 131–133
  - IME, 70, 132, 133
  - imec, 21, 70, 132, 133
  - OpSIS, 70
- free-space coupling, 385
- GDS layer map, 353
- GDS layout, 362–366
- germanium
  - absorption, 265
  - lasers, 304
- grating coupler, 163–182, 381
  - 2D FDTD, 170
  - 3D FDTD, 181
  - analytic, 169
  - Bragg condition, 166–168
  - circuits, 333
  - design methodology, 168
  - experimental, 373
  - fabrication non-uniformity, 377–379
  - focusing design, 179
  - mask layout, 180
  - return loss, 172, 330
  - S-parameters, 330
  - theory, 165
- grating coupling coefficient, 120
- group index, 59, 66–68
  - experimental, 67
- group velocity, 65
- high NA fibre, 185
- hybrid integration, 12
- hybrid laser, 301
- industry, 9
- insertion loss, 164
- integration, 15
- laser modelling, 39, 296–299
- lasers, 14, 295–306, 397
  - co-packaged, 299
  - epitaxial bonding, 301
  - etch-pit, 301
  - external, 295
  - external cavity, 300
  - germanium, 304
  - hybrid, 301
  - monolithic, 303
  - Raman, 306
- layer map, 353
- layout, 41, 362–366
- layout versus schematic, 350, 361
- lensed fibre, 383
- light sources, *see also* lasers, 14
- lithography simulation, 134
- losses, 69
- Mach–Zehnder
  - interferometer, 113–114
- mask layout, 41, 362–366
- Maxwell's equations, 30
- metal, 69
- micro-ring modulator, *see also* ring modulator, 226
- microscope, 393
- microwave modelling, 39

- mobility, 261
- mode
  - convergence test, 55
  - crossing, 63
  - edge coupler, 183
  - effective index, *see* effective index
  - energy density, 61
  - field intensities, 61
  - fundamental, 61
  - group index, *see* group index
  - mismatch, 162
  - mismatch loss, 70, 75, 184
  - overlap calculations, 73, 75, 184
  - polarization fraction, *see* polarization fraction
  - profile, 30, 53, 57, 59–62
  - single mode, 53, 63
  - slab waveguide, 53
  - solver, 28, 61
  - TE, 53, 57
  - TE-like, 61–63
  - TM, 53, 57
  - TM-like, 61, 62
  - wavelength dependence, 65
- modulators, 12, 217–241
- monolithic integration, 15
- multi-chip integration, 16
- multi-mode waveguides, 69
- multi-project wafer, 20
- OpSIS, *see also* foundry OpSIS, 21
- optical alignment, 394–396
- optical circuit modelling, 41
- optical communications, 8, 406
- optical coupling, 381–386
- optical cross-talk, 106–110
- optical losses
  - bends, 70
  - material, 69
  - metal, 69
  - mode mismatch, *see* mode mismatch loss
  - radiation, 70, 75
  - scattering, 69
  - substrate leakage, 70
  - wide waveguides, 69
- optical power budget, 400
- optical probe station, 389–397
- optical return loss, 164
- optical test equipment, 397
- optoelectronic modelling, 39
- oxide, 52
- packaging
  - electrical, 388
  - optical, 11, 385
- parasitic coupling, 106–110
- passivity, 324, 325
- penetration loss, 164
- perfectly matching layers, 33
- phase velocity, 65
- photonic circuit modelling, 40
- photonic crystals, 30
- photonic systems, 17
- photonic wire, *see* strip waveguide
- photonic–electronic integration, 15
- photons, 9
- PIN junction, 232–235
- pn-junction, 218–226
- polarization, 57, 190–193
  - conversion, 64
  - diversity, 191
  - fraction, 63, 65
  - management, 191
  - splitter rotator, 191
  - splitting grating couplers, 191
- probing, 387
- process design kit, 349
- process modelling, 39
- process stack, 5
- quality factor,  $Q$ , 35
- quasi-TE mode, *see* mode TE-like
- quasi-TM mode, *see* mode TM-like
- RC time constant
  - detector, 261
  - pn junction, 223, 225
- reciprocity, 38, 317, 320, 326
- refractive index
  - imaginary, 69
  - Lorentz model, 50
  - Palik data, 50
  - Sellmeier model, 50
  - silicon, 49
  - silicon dioxide, 51
  - temperature dependence, 50, 51
- responsivity, 259
- RF probing, 387
- rib waveguide, 68
  - directional couplers, 93–103
  - effective index, 66
  - effective index method, *see also* effective index method, 60
  - geometry, 52
  - mode profile, 60
- ridge waveguide, *see* strip waveguide
- ring modulator, 226–232, 406
- ring resonator, 115–117
  - circuit model, 330
  - fabrication non-uniformity, 372–377
- roughness, 69

- S-parameters, 317, 324
  - directional coupler, 320
  - FDTD, 320
  - grating coupler, 330
  - passivity, 324
  - passivity enforcement, 325
- scattering, 69
- schematic capture, 353
- schematic-driven layout, 350, 356
- semiconductor modelling, 39
- silicon
  - buried oxide, 49
  - optical absorption, 217
  - refractive index, 49
  - silicon-on-insulator, 49
  - substrate, 49
  - thickness variation, 49
  - wafer, 49
- silicon dioxide
  - cladding, 52
  - refractive index, 51
  - temperature dependence, 51
- silicon oxide
  - buried oxide, 49
- silicon photonic chip, 7
- simulation
  - analysis, 35
  - boundary conditions, 33
  - conformal mesh, 56
  - convergence test, 34, 55, 56
  - mesh, 32
  - mesh accuracy, 71
  - mesh grid, 56
  - mesh override, 56
  - mesh refinement, 57
  - mode expansion, 71
  - mode solver, 61
  - monitors, 33
  - movies, 71
  - optimization, 35
  - parameter sweep, 35
  - simulation boundaries, 55
  - simulation size, 56
  - simulation span, 56
  - simulation time, 56
  - staircase mesh, 56
  - volume, 32
- small signal modulation response, 228
- Soref, 217
- spiral gratings, 137
- splitter, 110
- spot-size converter, 383
- strip waveguide, 51
  - directional couplers, 105–106
  - effective index, 57
  - effective index method, *see also* effective index method, 59
  - geometry, 52
  - mode profile, 61–63
  - polarization fraction, 65
  - TE-like mode, 61–63
  - TM-like mode, 62
- strip-loaded ridge waveguide, *see* rib waveguide
- substrate leakage, 70
- supermode, 92
- TCAD, 39
- temperature control, 392
- temperature dependence
  - Bragg grating, 138
  - detector dark current, 280, 281
  - Mach–Zehnder, 241
  - ring resonator, 410
  - silicon, 50
- test equipment, 397
- test structures, 399
- thermal modelling, 40
- thermal phase shifter, 236–240, 400
- thermal tuning efficiency, 236, 408
- thermo-optic switch, 240–241
- through-silicon vias, 16
- tiling, 351
- transfer matrix method, 38, 121–123
- trimming, 400
- tuning, 234, 400
- variable optical attenuator, 232
- wafer, 4
- wave propagation, 31–38
- waveguide, 10
  - bends, *see* bent waveguides
  - compact model, 66
  - design, 53
  - directional couplers, 92–110
  - dispersion, 66
  - effective index, *see* effective index
  - evanescent field, 55
  - geometry, 52
  - group index, *see* group index
  - losses, 69
  - mode, *see* mode
  - numerical modelling, 53–75
  - oxide cladding, 52
  - parameters, 68
  - pn-junction, 65
  - rib, *see* rib waveguide
  - scattering loss, 61
  - single mode, 63
  - slab, 53–55, 57, 58
  - slab thickness, 57

|                                   |                                                       |
|-----------------------------------|-------------------------------------------------------|
| waveguide (cont.)                 | wavelength division multiplexing, 406                 |
| strip, <i>see</i> strip waveguide | wide waveguides, 69                                   |
| TE, 54, 59                        | wire bonding, 16, 388                                 |
| TM, 55                            |                                                       |
| wavelength dependence, 65, 67     | Y-branch, 110–112                                     |
| width, 63                         | yield, <i>see also</i> fabrication non-uniformity, 20 |